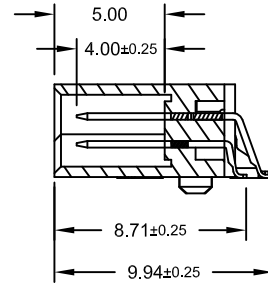
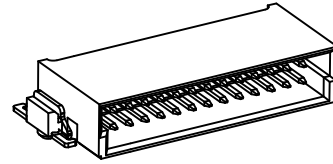
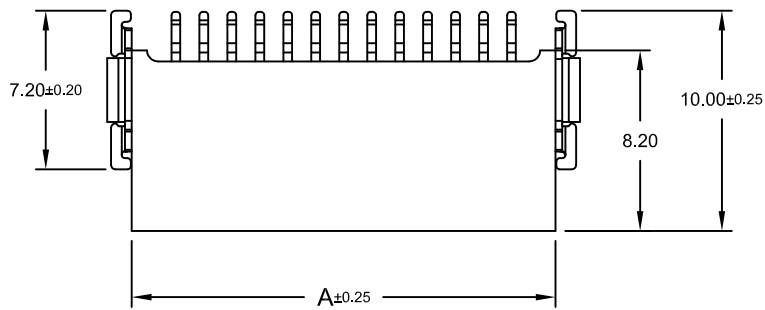


| REV. | DESCRIPTION | DATE | DRAWN |
|------|---------------------|------------|-------|
| A | NEW | 05.12.2013 | Ronny |
| B | add 60, 68 & 80 pin | 17.03.2014 | Ronny |
| C | correct coplanarity | 11.09.2014 | Ronny |



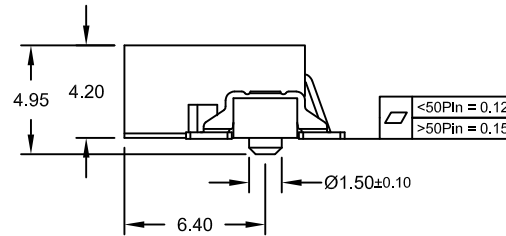
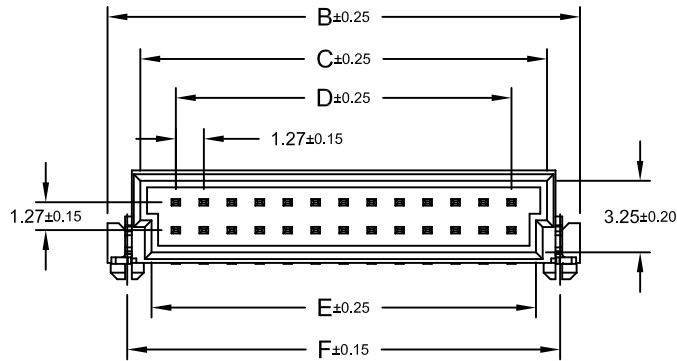
Order Code
MBC-xxx-BMH42-xx/11X

Packing Options

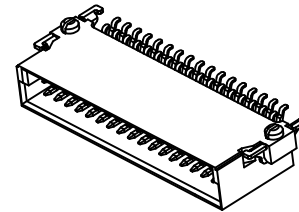
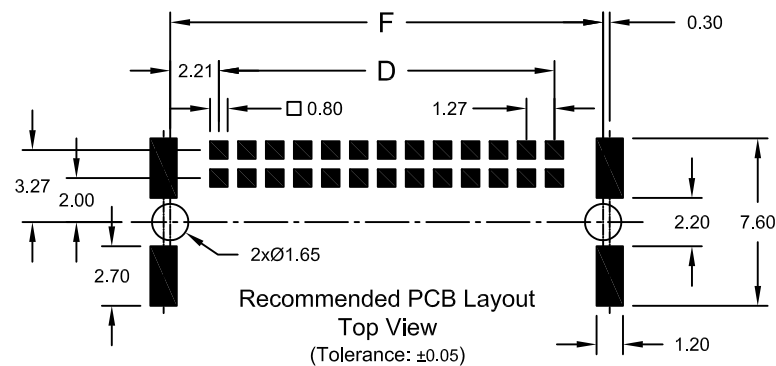
- C = tube
- G = reel

Plating

- 96 = tin / gold 5µ" (standard)
- Options:
- M95 = matte tin / gold flash
- 57 = gold flash / gold 10µ"



| No. of Pin | Dimension mm | | | | | |
|------------|--------------|-------|-------|-------|-------|-------|
| | A | B | C | D | E | F |
| 012 | 10,35 | 12,70 | 9,57 | 6,35 | 8,57 | 10,77 |
| 026 | 19,24 | 21,60 | 18,46 | 15,24 | 17,46 | 19,66 |
| 050 | 34,48 | 36,80 | 33,70 | 30,48 | 32,70 | 34,90 |
| 060 | 40,83 | 43,15 | 40,05 | 40,83 | 39,05 | 41,25 |
| 068 | 45,91 | 48,20 | 45,13 | 41,91 | 44,13 | 46,33 |
| 080 | 53,53 | 55,80 | 52,75 | 49,53 | 51,75 | 53,95 |



Materials

Contact: Copper Alloy
Plating: Gold, Tin or Duplex
*Duplex = Gold plated on contact area, Tin on solder area

Insulator: LCP UL 94V-0 (Black)

Lifetime: >500 mating cycles

Operating temperature: -55°C to +125°C
Processing temperature: +260°C ca. 10 sec.

Specifications Electrical

Current rating per contact: min. 1.1A @20°C
Insulation resistance: 10.000MΩ min.
Withstanding voltage: 500V AC
Contact resistance: 30mΩ max.



| UNIT | GENERAL TOLERANCE | | DRAWN | DATE | DWG. NO. | SHEET 1/1 |
|-------|-------------------|-------------|-------|------------|----------------------|-----------|
| mm | X.° ± | X. ± 0.30 | Ronny | 05.12.2013 | MBC-BMH42/11 | REV. C |
| SCALE | .X° ± | .X ± 0.25 | Hogi | 11.09.2014 | SERIES NO. | |
| | .XX° ± | .XX ± 0.15 | Hogi | 11.09.2014 | MBC-xxx-BMH42-xx/11X | |
| | .XXX° ± | .XXX ± 0.10 | | | | |

Multi BUS/Backplane Connector
B-Type Male SMT horizontal
1.27mm pitch height - 4,20mm
compatible to ERNI INTERact® Series SMC Type